The Capacitance Company KEVET CHARGED*

X5R Dielectric, 4VDC-50VDC (Commercial Grade)

Overview

KEMET's X5R dielectric features an 85°C maximum operating temperature and is considered "semi-stable." The Electronics Components, Assemblies & Materials Association (EIA) characterizes X5R dielectric as a Class II material. Components of this classification are fixed, ceramic dielectric capacitors suited for bypass and decoupling applications or for frequency discriminating circuits where Q and stability of capacitance characteristics are not critical. X5R exhibits a predictable change

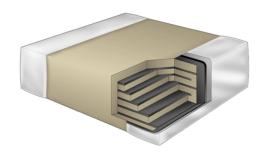
in capacitance with respect to time and voltage and boasts a minimal change in capacitance with reference to ambient temperature. Capacitance change is limited to ±15% from -55°C to +85°C.

Benefits

- -55°C to +85°C operating temperature range
- · Pb-Free and RoHS compliant
- · Temperature stable dielectric
- EIA 0201, 0402, 0603, 0805, 1206, and 1210 case sizes
- DC voltage ratings of 4V, 6.3V, 10V, 16V, 25V, 35V and 50V
- Capacitance offerings ranging from .01 μF to 100μF
- Available capacitance tolerances of ±10% and ±20%
- · Non-polar device, minimizing installation concerns
- 100% pure matte tin-plated termination finish allowing for excellent solderability

Applications

Typical applications include decoupling, bypass, and filtering.



Ordering Information

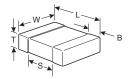
С	1206	С	107	M	9	Р	Α	С	TU
Ceramic	Case Size (L" x W")	Specification/ Series	Capacitance Code (pF)	Capacitance Tolerance	Voltage	Dielectric	Failure Rate/ Design	Termination Finish ²	Packaging/Grade (C-Spec) ²
	1005 = 01005 0201 0402 0603 0805 1206 1210	C = Standard	2 Sig. Digits + Number of Zeros	K = ±10% M = ±20%	7 = 4V 9 = 6.3V 8 = 10V 4 = 16V 3 = 25V 6 = 35V 5 = 50V	P = X5R	A = N/A	C = 100% Matte Sn	Blank = Bulk TU = 7" Reel Unmarked TM = 7" Reel Marked

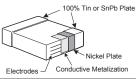
¹ Additional termination finish options may be available. Contact KEMET for details.

² Additional reeling or packaging options may be available. Contact KEMET for details.



Dimensions – Millimeters (Inches)





EIA Size Code	Metric Size Code	L Length	W Width	T Thickness	B Bandwidth	S Separation Min.	Mounting Technique
01005	0402	0.40 (.016) ± 0.02 (.001)	0.20 (.008) ± 0.02 (.001)		0.10 (.004) ± 0.03 (.001)	N/A	
0201	0603	0.60 (.024) ± 0.03 (.001)	$0.30 (.012) \pm 0.03 (.001)$		0.15 (.006) ± 0.05 (.002)	IN/A	Solder Reflow Only
0402	1005	1.00 (.040) ± 0.05 (.002)	$0.50 (.020) \pm 0.05 (.002)$	SSS	0.30 (.012) ± 0.10 (.004)	0.30 (.012)	
0603	1608	1.60 (.063) ± 0.15 (.006)	0.80 (.032) ± 0.15 (.006)	Thickness	0.35 (.014) ± 0.15 (.006)	0.70 (.028)	0.11.34
0805	2012	2.00 (.079) ± 0.20 (.008)	1.25 (.049) ± 0.20 (.008)	Ë	$0.50 (0.02) \pm 0.25 (.010)$	0.75 (.030)	Solder Wave or Solder Reflow
1206	3216	3.20 (.126) ± 0.20 (.008)	1.60 (.063) ± 0.20 (.008)	2 for	$0.50 (0.02) \pm 0.25 (.010)$		Golder Reliow
1210	3225	3.20 (.126) ± 0.20 (.008)	2.50 (.098) ± 0.20 (.008)	ple	$0.50 (0.02) \pm 0.25 (.010)$		
1812	4532	4.50 (.177) ± 0.30 (.012)	3.20 (.126) ± 0.30 (.012)	See Table	0.60 (.024) ± 0.35 (.014)	NI/A	
1825	4564	4.50 (.177) ± 0.30 (.012)	6.40 (.252) ± 0.40 (.016)	S _e	0.60 (.024) ± 0.35 (.014)	N/A	Solder Reflow Only
2220	5650	5.70 (.224) ± 0.40 (.016)	5.00 (.197) ± 0.40 (.016)		0.60 (.024) ± 0.35 (.014)		
2225	5664	5.60 (.220) ± 0.40 (.016)	6.40 (.248) ± 0.40 (.016)		0.60 (.024) ± 0.35 (.014)		

Qualification/Certification

Commercial grade products are subject to internal qualification. Details regarding test methods and conditions are referenced in Table 4, Performance and Reliability.

Environmental Compliance

Pb-Free and RoHS compliant

Electrical Parameters/Characteristics

Item	Parameters/Characteristics
Operating Temperature Range	-55°C to +85°C
Capacitance Change with Reference to +25°C and 0 Vdc Applied (TCC)	±15%
Aging Rate (Max % Cap Loss/Decade Hour)	4.0%
Dielectric Withstanding Voltage	250% of rated voltage (5 ± 1 seconds and charge/discharge not exceeding 50mA)
Dissipation Factor (DF) Maximum Limits @ 25°C	See Dissipation Factor Limit Table
Insulation Resistance (IR) Limit @ 25°C	See Insulation Resistance Limit Table (Rated voltage applied for 120 ± 5 secs @ 25°C)

Regarding Aging Rate: Capacitance measurements (including tolerance) are indexed to a referee time of 48 or 1000 Hours. Please refer to a part number specific datasheet for referee time details.

To obtain IR limit, divide $M\Omega$ - μ F value by the capacitance and compare to $G\Omega$ limit. Select the lower of the two limits.

Capacitance and Dissipation Factor (DF) measured under the following conditions:

1kHz \pm 50Hz and 1.0 \pm 0.2 Vrms if capacitance ≤10 μ F

120Hz \pm 10Hz and 0.5 ± 0.1 Vrms if capacitance >10 μ F

Note: When measuring capacitance it is important to ensure the set voltage level is held constant. The HP4284 & Agilent E4980 have a feature known as Automatic Level Control (ALC). The ALC feature should be switched to "ON".



Post Environmental Limits

	High Temperature Life, Biased Humidity, Moisture Resistance											
Dielectric	Rated DC Voltage	Capacitance Value	Cap Shift	IR								
	>25	A.II	3.0									
VED	25	All	7.5	. 200/	400/ of locking Lines							
X5R	<25	< 0.56µF	7.5	± 20%	10% of Initial Limit							
	<25	≥ 0.56µF	12.0									

Dissipation Factor Limit Table

Rated DC Voltage	Capacitance	Dissipation Factor (Limit)					
50V - 200V	All	3%					
25V	All	5%					
<25V	< 0.56µF	5%					
<25V	≥ 0.56µF	10%					

Insulation Resistance Limit Table

EIA Case Size	1000 megohm microfarads or 100GΩ	500 megohm microfarads or 10GΩ
0201	N/A	ALL
0402	< .012µF	≥ .012µF
0603	< .047µF	≥ .047µF
0805	< .047µF	≥ .047µF
1206	< 0.22µF	≥ 0.22µF
1210	< 0.39µF	≥ 0.39µF
1808	ALL	N/A
1812	< 2.2µF	≥ 2.2µF
1825	ALL	N/A
2220	< 10µF	≥ 10µF
2225	ALL	N/A



Table 1 - (1005 - 1210 Case Sizes)

		Serie	es	C10	005	C	02	01			C0	402)				C0(603					CO	305	5			C	120)6			(C12	10	
Сар	Cap	Voltage C	Code	7	9	7	9	4	7	9	8	4	3	5	7	9	8	4	3	5	7	9	8	4	3	5	9	8	4	3	1	9	8	4	3	6 5
Oup	Code	Voltage	DC	4	6.3	4	6.3	16	4	6.3	5	9	25	20	4	6.3	9	16	25	20	4	6.3	9	91	25	20	6.3	5	16	25	20	6.3	9	16	25	35
		Cap Toler	rance			Pro	odı	ıct	Ava	ilak	oilit	y ar	nd C	hip	Th	ick	nes	s C	Codes - See Table 2 for Chip Thickness Dimensions																	
10,000 pF	103	K	М			AB	AB	AB																												
12,000 pF	123	K	M							BB	BB	BB																								
15,000 pF 18,000 pF	153 183	K K	M M						BB BB	BB BB	BB BB	BB BB			ŀ																					
22,000 pF	223	K	M	UD	מנו				BB		BB	BB			l																					
27,000 pF	273	K	М						ВВ	ВВ	BB	BB																								
33,000 pF	333	К	М						ВВ	ВВ	ВВ	ВВ			İ						İ						l									
39,000 pF	393	K	М						ВВ	ВВ	BB	BB																								
47,000 pF	473	K	M						BB	BB	BB	BB																								
56,000 pF 68,000 pF	563 683	K K	M M						BB BB	BB BB	BB BB	BB BB																								
82,000 pF	823	K	M						BB	BB	BB	BB			l																					
0.10 µF	104	K	M			АВ	AB						UD																							
0.12 µF	124	К	М																																	
0.15 µF	154	K	М																																	
0.18 μF 0.22 μF	184 224	K K	M M						ВВ	ВВ																										
0.22 μF 0.27 μF	274	K	M						DD	DD					СС	cc	СС	CC									EB	EB	FR	EB						
0.27 µr 0.33 µF	334	ĸ	M												CC		CC										EB	EB		EB						
0.39 µF	394	К	М			İ			İ						СС	СС	CC	CC			İ						EB	EB				FD	FD	FD	FD	FD
0.47 µF	474	K	М												CC	CC	CC	CC	UD	UD		DC					EC			EC		FD	FD		FD	
0.56 µF	564	K	М												CC	CC					DD		DD				ED	ED		ED		FD	FD		FD	
0.68 µF	684 824	K K	M M												CC		CC				DE DF	DE	DE	DE			EE EF	EE EF		EE		FD FF	FD FF	FD FF	FD FF	
0.82 μF 1.0 μF	105	K	M						RR	ВВ	RR				CC	CC	CC		CC			DG				חוו				EH		FH	FH		FH	
1.2 µF	125	K	M							00	00						00		00		DC	DC		DC	00	UD	EC	EC	_	EC		FD			FD	
1.5 µF	155	К	М			İ									İ						DC		DC				EC	EC		EC		FD		FD	FD	
1.8 µF	185	K	М																		DD	DD	1	DD			EC	EC		EC		FD		FD		
2.2 µF	225	K	М						BB¹	BB¹					CC	CC	CC	CC			DD	DD	1				EE	EE			UD			FG		
2.7 µF 3.3 µF	275 335	K K	M M						BB¹							CC1					DL	DL	DL				EF EH	EF	EF	EF		FG FH		FG FH		
3.9 µF	395	K	M						טט												DH		DH				EH	EH		EH		FJ	FJ		FJ	
4.7 µF	475	K	M						BC ²						СС	СС	СС	UD				DG			DG		EH				EH			FK		
5.6 µF	565	K	М																		DH	DH	DH				EK	EK	EH			FG		FG		
6.8 µF	685	K	М																		DH	DH	DH				EK		EH			FJ		FJ	FJ	
8.2 µF	825	K	M						חוו	III.	III.	III.	III.		CC1	001					D~	D0	D.C.	D.C.			ED		EH			FK		FK		ET1
10 μF 12 μF	106 126	K K	M M						עט	עט	עט	עט	UD		loo,	100'					المرا	DG	טפ	DG			EH	EH	EH	EH		FK FD		FK FG	гП	FI
15 µF	156	K	M			l									l						l											FF	FF			
18 µF	186	K	M			l			İ						İ						l						l					FG	FG			
22 µF	226	K	М						UD												DG	DG ¹					EH	EH				FH	FH	FJ		
27 µF	276	K	М																																	
33 μF 39 μF	336 396	K	M M																																	
39 μF 47 μF	476	K K	M												UD						DH1	DG					EH1	EH1				FS1	FS	FS1		
100 µF	107	K	M																								EH1							UD		
		Voltage	DC	4	6.3	4	6.3	16	4	6.3	5	16	25	20	4	6.3	9	16	25	20	4	6.3	9	9	25	20	6.3	9	16	25	20	6.3		16		35
Сар	Cap Code	Voltage C	Code	7	9	7	9	4	7	9	8	3	5	4	7	9	8	4	3	5	7	9	8	4	3	5	9	8	4	3	5	9	8	4	3	6 5
	Joue	Serie	s	C10	005	С	02)1			C0	402					CO	603					CO	305				С	120	6			(C12	10	

UD = Under Development

 xx^1 Available only in K,M tolerance xx^2 Available only in M tolerance.

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Table 2 – Chip Thickness/Packaging Quantities

Thickness	Chip	Thickness ±	QTY per Reel	QTY per Reel	QTY per Reel	QTY per Reel	QTY per Bulk
Code	Size	Range (mm)	7" Plastic	13" Plastic	7" Paper	13" Paper	Cassette
AA	1005	0.20 ± 0.02			15000		
AB BB	0201 0402	0.30 ± 0.03 0.50 ± 0.05			15000 10000	50000	50000
BC	0402	0.50 ± 0.10			10000	50000	50000
PA CB	0508 0603	0.80 ± 0.10 0.80 ± 0.07	4000	10000	4000	10000	15000
CC	0603	0.80 ± 0.10			4000	10000	15000
CD MA	0603 0612	0.80 ± 0.15 0.80 ± 0.10	4000	10000	4000	10000	15000
DB	0805	0.60 ± 0.10	4000	10000	4000	10000	15000
DC DD	0805 0805	0.78 ± 0.10 0.90 ± 0.10			4000 4000	10000 10000	15000 15000
DL	0805	0.95 ± 0.10	4000	10000	4000	10000	10000
DE DF	0805 0805	1.00 ± 0.10 1.10 ± 0.10	2500 2500	10000 10000			
DG	0805	1.25 ± 0.15	2500	10000			
DH EB	0805 1206	1.25 ± 0.20 0.78 ± 0.10	2500 4000	10000 10000	4000	10000	
EK	1206	0.80 ± 0.10	2000	8000	4000	10000	
EC EN	1206 1206	0.90 ± 0.10 0.95 ± 0.10	4000 4000	10000 10000			
ED	1206	1.00 ± 0.10	2500	10000			
EE EF	1206 1206	1.10 ± 0.10 1.20 ± 0.15	2500 2500	10000 10000			1
EM	1206	1.25 ± 0.15	2500	10000	Package (Quantity	
EG EH	1206 1206	1.60 ± 0.15 1.60 ± 0.20	2000 2000	8000 8000		•	
EJ	1206	1.70 ± 0.20	2000	8000		Finished Chip	
FB FC	1210	0.78 ± 0.10	4000 4000	10000 10000	Thickness	Specifications	
FD FD	1210 1210	0.90 ± 0.10 0.95 ± 0.10	4000	10000			
FE	1210	1.00 ± 0.10	2500	10000 10000			
FF FG	1210 1210	1.10 ± 0.10 1.25 ± 0.15	2500 2500	10000			
FL	1210	1.40 ± 0.15	2000	8000			
FO FH	1210 1210	1.50 ± 0.20 1.55 ± 0.15	2000 2000	8000 8000			
FP	1210	1.60 ± 0.20	2000	8000			
FM FJ	1210 1210	1.70 ± 0.20 1.85 ± 0.20	2000 2000	8000 8000			
FN FT	1210	1.85 ± 0.20	2000 1500	8000			
FI FK	1210 1210	1.90 ± 0.20 2.10 ± 0.20	2000	4000 8000			
FR FS	1210	2.25 ± 0.20 2.50 ± 0.20	2000 1000	8000 4000			
FV	1210 1210	3.35 ± 0.10	500	1800			
FW PA	1210 1220	6.15 ± 0.15 0.80 ± 0.10	200 4000	1000 10000			
MA	1632	0.80 ± 0.10 0.80 ± 0.10	4000	10000			
NA NB	1706 1706	0.90 ± 0.10 1.00 ± 0.10	4000 4000	10000 10000			
NC	1706	1.00 ± 0.10	4000	10000			
LD LE	1808 1808	0.90 ± 0.10 1.00 ± 0.10	2500 2500	10000 10000			
LF	1808	1.00 ± 0.15	2500	10000			
LA LB	1808 1808	1.40 ± 0.15 1.60 ± 0.15	1000 1000	4000 4000			
LC	1808	2.00 ± 0.15	1000	4000			
GB GC	1812 1812	1.00 ± 0.10 1.10 ± 0.10	1000 1000	4000 4000			
GD	1812	1.25 ± 0.15	1000	4000			
GE GH	1812 1812	1.30 ± 0.10 1.40 ± 0.15	1000 1000	4000 4000			
GF	1812	1.50 ± 0.10	1000	4000			
GG GK	1812 1812	1.55 ± 0.10 1.60 ± 0.20	1000 1000	4000 4000			
GJ	1812	1.70 ± 0.15	1000	4000			
GN GL	1812 1812	1.70 ± 0.20 1.90 ± 0.20	1000 1000	4000 4000			
GM	1812	2.00 ± 0.20	1000	4000			
GO GP	1812 1812	2.50 ± 0.20 2.65 ± 0.35	500 500	2000 1400			
GR	1812	5.00 ± 0.50	350	1000			
HB HC	1825 1825	1.10 ± 0.15 1.15 ± 0.15	1000 1000	4000 4000			
HD	1825	1.30 ± 0.15	1000	4000			
HE HF	1825 1825	1.40 ± 0.15 1.50 ± 0.15	1000 1000	4000 4000			
Thickness Code	Chip Size	Thickness ± Range (mm)	QTY per Reel 7" Plastic	QTY per Reel 13" Plastic	QTY per Reel 7" Paper	QTY per Reel 13" Paper	QTY per Bulk Cassette



Table 2 - Chip Thickness/Packaging Quantities con't

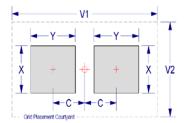
Thickness	Chip	Thickness ±	QTY per Reel	QTY per Reel	QTY per Reel	QTY per Reel	QTY per Bulk
Code	Size	Range (mm)	7" Plastic	13" Plastic	13" Plastic 7" Paper		Cassette
HG	1825	1.60 ± 0.20	1000	4000			
JB	2220	1.00 ± 0.15	1000	4000			
JC	2220	1.10 ± 0.15	1000	4000			
JD	2220	1.30 ± 0.15	1000	4000			
JE	2220	1.40 ± 0.15	1000	4000			
JF	2220	1.50 ± 0.15	1000	4000			
JP	2220	1.60 ± 0.20	1000	4000			
JG	2220	1.70 ± 0.15	1000	4000			
j JH	2220	1.80 ± 0.15	1000	4000			
JO	2220	2.40 ± 0.15	500	2000			
JP	2220	3.50 ± 0.30	250	850			
JR	2220	5.00 ± 0.50	150	600			
i KB	2225	1.00 ± 0.15	1000	4000			
KC	2225	1.10 ± 0.15	1000	4000			
KD	2225	1.30 ± 0.15	1000	4000			
KE	2225	1.40 ± 0.15	1000	4000			
KF	2225	1.60 ± 0.20	1000	4000			
Thickness	Chip	Thickness ±	QTY per Reel	QTY per Reel	QTY per Reel	QTY per Reel	QTY per Bulk
Code	Size	Range (mm)	7" Plastic	13" Plastic	7" Paper	13" Paper	Cassette

Table 3 – Chip Capacitor Land Pattern Design Recommendations per IPC-7351

EIA Size Code	Metric Size Code		Maxi	sity Lev mum (M rotrusio	Most))	Density Level B: Median (Nominal) Land Protrusion (mm)					Density Level C: Minimum (Least) Land Protrusion (mm)				
Oode	Oode	С	Υ	Х	V1	V2	С	Υ	Х	V1	V2	С	Υ	Х	V1	V2
01005	0402	0.33	0.46	0.43	1.60	0.90	0.28	0.36	0.33	1.30	0.70	0.23	0.26	0.23	1.00	0.50
0201	0603	0.38	0.56	0.52	1.80	1.00	0.33	0.46	0.42	1.50	0.80	0.28	0.36	0.32	1.20	0.60
0402	1005	0.50	0.72	0.72	2.20	1.20	0.45	0.62	0.62	1.90	1.00	0.40	0.52	0.52	1.60	0.80
0603	1608	0.90	1.15	1.10	4.00	2.10	0.80	0.95	1.00	3.10	1.50	0.60	0.75	0.90	2.40	1.20
0805	2012	1.00	1.35	1.55	4.40	2.60	0.90	1.15	1.45	3.50	2.00	0.75	0.95	1.35	2.80	1.70
1206	3216	1.60	1.35	1.90	5.60	2.90	1.50	1.15	1.80	4.70	2.30	1.40	0.95	1.70	4.00	2.00
1210	3225	1.60	1.35	2.80	5.65	3.80	1.50	1.15	2.70	4.70	3.20	1.40	0.95	2.60	4.00	2.90
1808	4520	2.30	1.75	2.30	7.40	3.30	2.20	1.55	2.20	6.50	2.70	2.10	1.35	2.10	5.80	2.40
1812	4532	2.15	1.60	3.60	6.90	4.60	2.05	1.40	3.50	6.00	4.00	1.95	1.20	3.40	5.30	3.70
1825	4564	2.15	1.60	6.90	6.90	7.90	2.05	1.40	6.80	6.00	7.30	1.95	1.20	6.70	5.30	7.00
2220	5650	2.75	1.70	5.50	8.20	6.50	2.65	1.50	5.40	7.30	5.90	2.55	1.30	5.30	6.60	5.60
2225	5664	2.70	1.70	6.90	8.10	7.90	2.60	1.50	6.80	7.20	7.30	2.50	1.30	6.70	6.50	7.00

Density Level A: For low-density Product applications. Recommended for wave solder applications and provides a wider process window for reflow solder processes. KEMET only recommends wave soldering of EIA 0603, 0805 and 1206 case sizes.

Density Level B: For products with a moderate level of component density. Provides a robust solder attachment condition for reflow solder processes. **Density Level C:** For high component density product applications. Before adapting the minimum land pattern variations the user should perform qualification testing based on the conditions outlined in IPC standard 7351 (IPC-7351).





Soldering Process

Recommended Soldering Technique:

- Solder wave or solder reflow for EIA case sizes 0603, 0805 and 1206
- · All other EIA case sizes are limited to solder reflow only

Recommended Soldering Profile:

KEMET recommends following the guidelines outlined in IPC/JEDEC J-STD-020

Table 4 – Performance & Reliability: Test Methods and Conditions

Stress	Reference	Test or Inspection Method
Terminal Strength	JIS-C-6429	Appendix 1, Note: Force of 1.8kg for 60 seconds.
Board Flex	JIS-C-6429	Appendix 2, Note: 2mm (min) for all except 3mm for C0G.
		Magnification 50 X. Conditions:
Caldarahilitu	J-STD-002	a) Method B, 4 hours @ 155°C, dry heat @ 235°C
Solderability	J-51D-002	b) Method B @ 215°C category 3
		c) Method D, category 3 @ 260°C
Temperature Cycling	JESD22 Method JA-104	1000 Cycles (-55°C to +125°C), Measurement at 24 hours. +/- 2 hours after test conclusion.
D: 111 : 15	MIL OTD 000 M II 1400	Load Humidity: 1000 hours 85°C/85%RH and Rated Voltage. Add 100K ohm resistor. Measurement at 24 hours. +/- 2 hours after test conclusion.
Biased Humidity	MIL-STD-202 Method 103	Low Volt Humidity: 1000 hours 85°C/85%RH and 1.5V. Add 100K ohm resistor. Measurement at 24 hours. +/- 2 hours after test conclusion.
Moisture Resistance	MIL-STD-202 Method 106	t = 24 hours/cycle. Steps 7a & 7b not required. Unpowered. Measurement at 24 hours. +/- 2 hours after test conclusion.
Thermal Shock	MIL-STD-202 Method 107	-55°C/+125°C. Note: Number of cycles required-300, Maximum transfer time-20 seconds, Dwell time-15 minutes. Air-Air.
High Temperature Life	MIL-STD-202 Method 108 / EIA -198	1000 hours at 125°C (85°C for X5R, Z5U and Y5V) with 2 X rated voltage applied.
Storage Life	MIL-STD-202 Method 108	150°C, 0VDC, for 1000 Hours.
Mechanical Shock	MIL-STD-202 Method 213	Figure 1 of Method 213, Condition F.
Resistance to Solvents	MIL-STD-202 Method 215	Add aqueous wash chemical - OKEM Clean or equivalent.

Storage and Handling

Ceramic chip capacitors should be stored in normal working environments. While the chips themselves are quite robust in other environments, solderability will be degraded by exposure to high temperatures, high humidity, corrosive atmospheres, and long term storage. In addition, packaging materials will be degraded by high temperature – reels may soften or warp, and tape peel force may increase. KEMET recommends that maximum storage temperature not exceed 40°C, and maximum storage humidity not exceed 70% relative humidity. In addition, temperature fluctuations should be minimized to avoid condensation on the parts, and atmospheres should be free of chlorine and sulfur bearing compounds. For optimized solderability, chip stock should be used promptly, preferably within 1.5 years of receipt.



Tape & Reel Packaging Information

KEMET offers Multilayer Ceramic Chip Capacitors packaged in 8mm, 12mm and 16mm tape on 7" and 13" reels in accordance with EIA standard 481. This packaging system is compatible with all tape fed automatic pick and place systems. See Table 2 for details on reeling quantities for commercial chips.

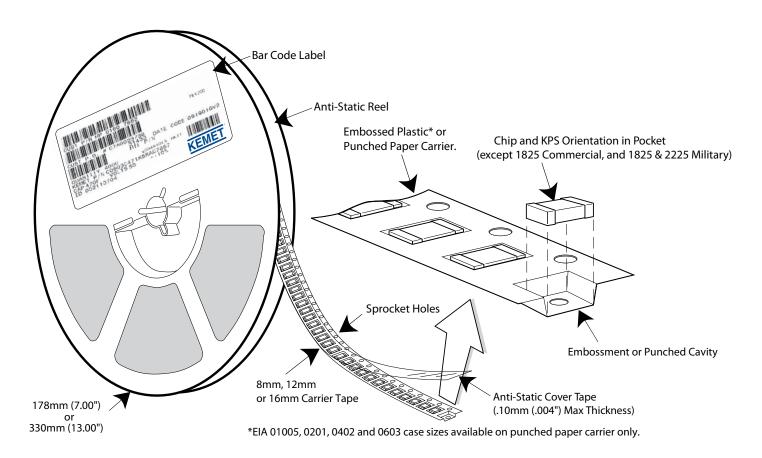


Table 5 – Carrier Tape Configuration (mm)

EIA Case Size	Tape size (W)*	Pitch (P ₁)*
01005 - 0402	8	2
0603 - 1210	8	4
1805 - 1808	12	4
≥ 1812	12	8
KPS 1210	12	8
KPS 1812 & 2220	16	12
Array 0508 & 0612	8	4

^{*}Refer to Figure 1 for W and P, carrier tape reference locations.

^{*}Refer to Table 6 for tolerance specifications.



Figure 1 – Embossed (Plastic) Carrier Tape Dimensions

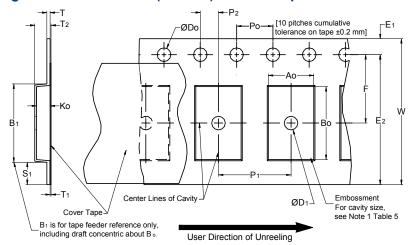


Table 6 - Embossed (Plastic) Carrier Tape Dimensions

Metric will govern

	Constant Dimensions — Millimeters (Inches)								
Tape Size	D ₀	D₁ Min. Note 1	E ₁	P_0	P ₂	R Ref. Note 2	S ₁ Min. Note 3	T Max.	T ₁ Max.
8mm		1.0 (0.039)				25.0 (0.984)			
12mm	1.5 +0.10/-0.0 (0.059 +0.004/-0.0)	1.5	1.75 ± 0.10 (0.069 ± 0.004)	4.0 ± 0.10 (0.157 ± 0.004)	$ 2.0 \pm 0.05 \\ (0.079 \pm 0.002) $	30	0.600 (0.024)	0.600 (0.024)	0.100 (0.004)
16mm		(0.059)				(1.181)			
			Variable Dime	ensions — Milli	meters (Inche	s)			
Tape Size	Pitch	B₁ Max. Note 4	E ₂ Min.	F	P ₁	T ₂ Max	W Max	A ₀ ,B	. & K ₀
8mm	Single (4mm)	4.35 (0.171)	6.25 (0.246)	3.5 ± 0.05 (0.138 ± 0.002)	4.0 ± 0.10 (0.157 ± 0.004)	2.5 (0.098)	8.3 (0.327)		
12mm	Single (4mm) & Double (8mm)	8.2 (0.323)	10.25 (0.404)	5.5 ± 0.05 (0.217 ± 0.002)	8.0 ± 0.10 (0.315 ± 0.004)	4.6 (0.181)	12.3 (0.484)	No	te 5
16mm	Triple (12mm)	12.1 (0.476)	14.25 (0.561)	5.5 ± 0.05 (0.217 ± 0.002)	8.0 ± 0.10 (0.315 ± 0.004)	4.6 (0.181)	16.3 (0.642)		

- 1. The embossment hole location shall be measured from the sprocket hole controlling the location of the embossment. Dimensions of embossment location and hole location shall be applied independent of each other.
- 2. The tape with or without components shall pass around R without damage (see Figure 5).
- 3. If S₁<1.0 mm, there may not be enough area for cover tape to be properly applied (see EIA Document 481 paragraph 4.3 (b)).
- 4. B1 dimension is a reference dimension for tape feeder clearance only.
- 5. The cavity defined by A_0 , B_0 and K_0 shall surround the component with sufficient clearance that:
 - (a) the component does not protrude above the top surface of the carrier tape.
 - (b) the component can be removed from the cavity in a vertical direction without mechanical restriction, after the top cover tape has been removed.
 - (c) rotation of the component is limited to 20° maximum for 8 and 12mm tapes and 10° maximum for 16mm tapes (see Figure 3).
 - (d) lateral movement of the component is restricted to 0.5 mm maximum for 8mm and 12mm wide tape and to 1.0mm maximum for 16mm tape (see Figure 4).
 - (e) for KPS Series product A_0 and B_0 are measured on a plane 0.3mm above the bottom of the pocket.
 - (f) see Addendum in EIA Document 481 for standards relating to more precise taping requirements.



Figure 2 – Punched (Paper) Carrier Tape Dimensions

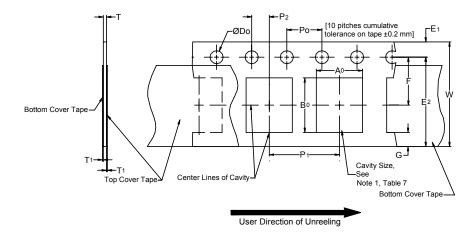


Table 7 – Punched (Paper) Carrier Tape Dimensions

Metric will govern

	Constant Dimensions — Millimeters (Inches)								
Tape Size	D ₀	E ₁	P ₀	P ₂	T ₁ Max	G Min	R Ref. Note 2		
8mm	1.5 +0.10-0.0 (0.059 +0.004, -0.0)	1.75 ±0.10 (0.069 ±0.004)	4.0 ±0.10 (0.157 ±0.004)	2.0 ±0.05 (0.079 ±0.002)	0.10 (.004) Max.	0.75 (.030)	25 (.984)		
	Variable Dimensions — Millimeters (Inches)								
Tape Size	Pitch	E2 Min	F	P ₁	T Max	W Max	A_0B_0		
8mm	Half (2mm)	6.25	3.5 ± 0.05	2.0 ± 0.05 (0.079 ± 0.002)	1.1	8.3 (0.327)	Note 5		
8mm	Single (4mm)	(0.246)	(0.138 ± 0.002)	4.0 ± 0.10 (0.157 ± 0.004)	(0.098)	8.3 (0.327)	NOTE 5		

^{1.} The cavity defined by A_{o} , B_{o} and T shall surround the component with sufficient clearance that:

a) the component does not protrude beyond either surface of the carrier tape.

b) the component can be removed from the cavity in a vertical direction without mechanical restriction, after the top cover tape has been removed.

d) lateral movement of the component is restricted to 0.5 mm maximum (see Figure 4).

e) see Addendum in EIA Document 481 for standards relating to more precise taping requirements.

^{2.} The tape with or without components shall pass around R without damage (see Figure 5).



Packaging Information Performance Notes

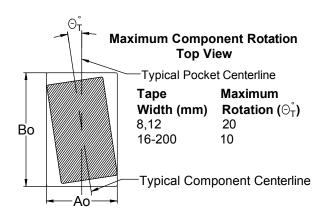
- 1. Cover Tape Break Force: 1.0 Kg Minimum.
- 2. Cover Tape Peel Strength: The total peel strength of the cover tape from the carrier tape shall be:

Tape Width	Peel Strength
8mm	0.1 Newton to 1.0 Newton (10gf to 100gf)
12mm & 16mm	0.1 Newton to 1.3 Newton (10gf to 130gf)

The direction of the pull shall be opposite the direction of the carrier tape travel. The pull angle of the carrier tape shall be 165° to 180° from the plane of the carrier tape. During peeling, the carrier and/or cover tape shall be pulled at a velocity of 300±10 mm/minute.

3. Labeling: Bar code labeling (standard or custom) shall be on the side of the reel opposite the sprocket holes. Refer to EIA-556 and EIA-624.

Figure 3 – Maximum Component Rotation



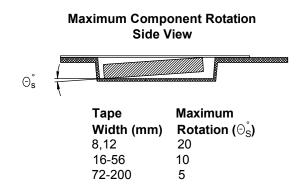


Figure 4 – Maximum Lateral Movement

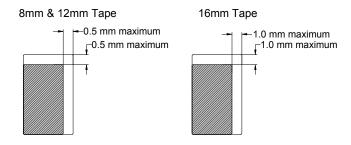


Figure 5 – Bending Radius

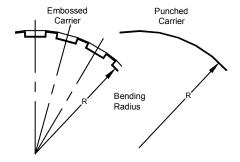
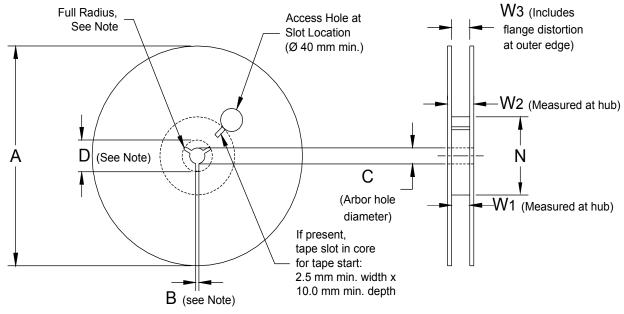




Figure 6 - Reel Dimensions



Note: Drive spokes optional; if used, dimensions B and D shall apply.

Table 8 - Reel Dimensions

Metric will govern

	Constant Dimensions — Millimeters (Inches)								
Tape Size	A	B Min	С	D Min					
8mm	178 ± 0.20								
12mm	(7.008 ± 0.008) or	1.5 (0.059)	13.0 +0.5/-0.2 (0.521 +0.02/-0.008)	20.2 (0.795)					
16mm	$\begin{array}{c} -330 \pm 0.20 \\ (13.000 \pm 0.008) \end{array}$,	,	, ,					
	Variable	Dimensions — Millimeter	rs (Inches)						
Tape Size	N Min	W ₁	W ₂ Max	W ₃					
8mm		8.4 +1.5/-0.0 (0.331 +0.059/-0.0)	14.4 (0.567)						
12mm	50 (1.969)	12.4 +2.0/-0.0 (0.488 +0.078/-0.0)	18.4 (0.724)	Shall accommodate tape width without interference					
16mm		16.4 +2.0/-0.0 (0.646 +0.078/-0.0)	22.4 (0.882)						



Figure 7 – Tape Leader & Trailer Dimensions

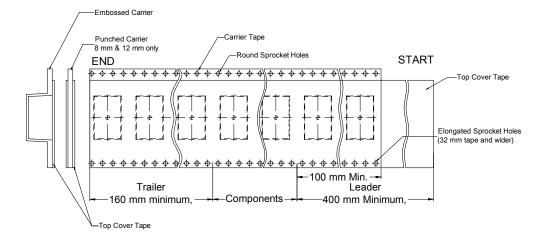


Figure 8 – Maximum Camber

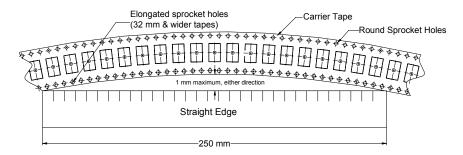




Figure 9 – Bulk Cassette Packaging (Ceramic Chips Only)

Meets Dimensional Requirements IEC-286 and EIAJ 7201

Unit mm *Reference

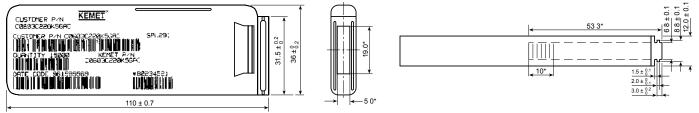


Table 9 - Capacitor Dimensions for Bulk Cassette

Cassette Packaging - Millimeters

EIA Size Code	Metric Size Code	L Length	W Width	B Bandwidth	S Separation minimum	T Thickness	Number of Pcs/Cassette
0402	1005	1.0 ± 0.05	0.5 ± 0.05	0.2 to 0.4	0.3	0.5 ± .05	50,000
0603	1608	1.6 ± 0.07	0.8 ± 0.07	0.2 to 0.5	0.7	0.8 ± .07	15,000

Table 10 – Capacitor Marking

Laser marking is available as an extra-cost option for most KEMET ceramic chips. Such marking is two sided, and includes a K to identify KEMET, followed by two characters (per EIA-198) to identify the capacitance value. Note that marking is not available for any Y5V chip. In addition, the 0603 marking option is limited to the K only. (Marking Optional – Not Available for 0402 Size)

Numeral		Ca	apacita	nce (p	F) For V	arious N	umeral Ide	entifiers	
Alpha	9	0	1	2	3	4	5	6	7
Character	0.1	1	10	100	1000	10000	100000	1000000	10000000
A									
В	0.11	1.1	11	110	1100	11000	110000	1100000	11000000
С	0.12	1.2	12	120	1200	12000	120000	1200000	12000000
D	0.13	1.3	13	130	1300	13000	130000	1300000	13000000
E	0.15	1.5	15	150	1500	15000	150000	1500000	15000000
F	0.16	1.6	16	160	1600	16000	160000	1600000	16000000
G	0.18	1.8	18	180	1800	18000	180000	1800000	18000000
H	0.2	2	20	200	2000	20000	200000	2000000	20000000
J	0.22	2.2	22	220	2200	22000	220000	2200000	22000000
K	0.24	2.4	24	240	2400	24000	240000	2400000	24000000
L	0.27	2.7	27	270	2700	27000	270000	2700000	27000000
M	0.3	3	30	300	3000	30000	300000	3000000	3000000
N	0.33	3.3	33	330	3300	33000	330000	3300000	33000000
P	0.36	3.6	36	360	3600	36000	360000	3600000	36000000
Q	0.39	3.9	39	390	3900	39000	390000	3900000	39000000
R	0.43	4.3	43	430	4300	43000	430000	4300000	43000000
S	0.47	4.7	47	470	4700	47000	470000	4700000	47000000
T	0.51	5.1	51	510	5100	51000	510000	5100000	51000000
U	0.56	5.6	56	560	5600	56000	560000	5600000	56000000
V	0.62	6.2	62	620	6200	62000	620000	6200000	62000000
W	0.68	6.8	68	680	6800	68000	680000	6800000	68000000
Х	0.75	7.5	75	750	7500	75000	750000	7500000	75000000
Y	0.82	8.2	82	820	8200	82000	820000	8200000	82000000
Z	0.91	9.1	91	910	9100	91000	910000	9100000	91000000
а	0.25	2.5	25	250	2500	25000	250000	2500000	25000000
b	0.35	3.5	35	350	3500	35000	350000	3500000	35000000
d	0.4	4	40	400	4000	40000	400000	4000000	40000000
е	0.45	4.5	45	450	4500	45000	450000	4500000	45000000
f	0.5	5	50	500	5000	50000	500000	5000000	50000000
m	0.6	6	60	600	6000	60000	600000	6000000	60000000
n	0.7	7	70	700	7000	70000	700000	7000000	7000000
t	0.8	8	80	800	8000	80000	800000	8000000	80000000
٧	0.9	9	90	900	9000	90000	900000	9000000	9000000



Example shown is 1,000 pF capacitor



Other KEMET Resources

Tools						
Resource	Location					
Configure A Part: CapEdge	http://capacitoredge.kemet.com					
SPICE & FIT Software	http://www.kemet.com/spice					
Search Our FAQs: KnowledgeEdge	http://www.kemet.com/keask					

Product Information						
Resource	Location					
Products	http://www.kemet.com/products					
Technical Resources (Including Soldering Techniques)	http://www.kemet.com/technicalpapers					
RoHS Statement	http://www.kemet.com/rohs					
Quality Documents	http://www.kemet.com/qualitydocuments					

Product Request					
Resource	Location				
Sample Request	http://www.kemet.com/sample				
Engineering Kit Request	http://www.kemet.com/kits				

Contact						
Resource	Location					
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Contact Us	http://www.kemet.com/contact					
Investor Relations	http://www.kemet.com/ir					
Call Us	1-877-MyKEMET					
Twitter	http://twitter.com/kemetcapacitors					

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Rome, Italy

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Beijing, China

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Shanghai, China Tel: 86-21-6447-0707

Taipei, Taiwan Tel: 886-2-27528585

Southeast Asia

Singapore Tel: 65-6586-1900

Penang, Malaysia Tel: 60-4-6430200

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